

Notification Number:	20220630000.0	Notification Date:	July 05, 2022
Title:	Datasheet for SNx4HC112, SNx4HC175, SNx4HC368, and CDx4HCT373		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN54HC112, SN74HC112

SCLS099H – DECEMBER 1982 – REVISED JUNE 2022

Changes from Revision G (February 2022) to Revision H (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, N was 67 is now 89.1.....4



SN54HC175, SN74HC175

SCLS299F – JANUARY 1996 – REVISED JUNE 2022

Changes from Revision E (February 2022) to Revision F (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, DB was 67 is now 102.7, N was 82 is now 60.5, NS was 64 is now 88.6, PW was 108 is now 137.5.....4



SN54HC368, SN74HC368

SCLS310F – JANUARY 1996 – REVISED JUNE 2022

Changes from Revision E (February 2022) to Revision F (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, N was 67 is now 68.6, NS was 64 is now 87.4, PW was 108 is now 137.5.....4



CD54HCT373, CD74HCT373

SCLS453E – FEBRUARY 2001 – REVISED JUNE 2022

Changes from Revision D (February 2022) to Revision E (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. DW was 69 is now 109.1, N was 58 is now 84.6.....4

The datasheet number will be changing.

Device Family	Change From:	Change To:
SNx4HC112	SCLS099G	SCLS099H
SNx4HC175	SCLS299E	SCLS299F
SNx4HC368	SCLS310E	SCLS310F
CDx4HCT373	SCLS453D	SCLS453E

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/SN74HC112>

<https://www.ti.com/product/SN74HC175>

<https://www.ti.com/product/SN74HC368>

<https://www.ti.com/product/CD74HCT373> **Error! Bookmark not defined.**

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

CD74HCT373E	SN74HC112DT	SN74HC175NE4	SN74HC368DR
CD74HCT373M	SN74HC112N	SN74HC175NSR	SN74HC368N
CD74HCT373M96	SN74HC175D	SN74HC175PW	SN74HC368NE4
CD74HCT373M96G4	SN74HC175DBR	SN74HC175PWR	SN74HC368NSR
CD74HCT373MG4	SN74HC175DG4	SN74HC368D	SN74HC368PW
SN74HC112D	SN74HC175DR	SN74HC368DG4	SN74HC368PWR
SN74HC112DR	SN74HC175N		

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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